ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Comp © Copyright 2005. Il international and Par	C, Bannock	burn, Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declar the declaration	ation of the nencompas	substances ses all lowe	within the er level mat	manufacture erials for wh	er listed ite	m. Note: i nufacture	if the item is an as r has engineering	sembly with lowe responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
Supplier Information															
Company name*	Company uni	Company unique ID			Unique ID Authority					Response Date*					
onsemi											2025-08-16				
Contact Name	Title - Contac	Title - Contact			Phone - Contact*					Email - Contact*					
Product-Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
Authorized Representative*	Title - Repres	Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Da	ate Versio	e Version Manufacturing Site		ring Site	W	'eight*	UOM	Unit Type	
	NCV87 2G			5.0V/150mA LDO w WDI/EN/RO		2025-08-16			PH1		69	9.85	mg	Each	
Manufacturing Proccess Information	ion						·	·							
Terminal Plating / Grid Array Ma	terial	Ferminal Base A	Alloy	J-STD-020 MS	L Rating	Peak Process Body Ter		Temperatu	erature Max Time at Peak		Temperatu	Cemperature Number of Reflow Cycles		les	
Precious metal (e.g. Ag,Au, NiP Sn)			CU Alloy 2			260		С	30		second	seconds 3			
Comments															
TTENTION: MSL 2 Rated item require	Dry Pack (after electrical	test)												
or more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.57	mg	Supplier	Silicon (Si)	7440-21-3		1.57	mg
Die Attach	0.44	mg		Epoxy resin	proprietary data		0.022	mg
			Supplier	Poly(oxypropylene)diamine	9046-10-0		0.0088	mg
			Supplier	Copper(II) Oxide (CuO)	1317-38-0		0.0132	mg
			Supplier	Fatty acids, C18-unsatd., dimers, polymers with epichlorhydrin	68475-94-5		0.0132	mg
			Supplier	Silver (Ag)	7440-22-4		0.3608	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.022	mg
Lead Frame	37.61	mg	Supplier	Zinc (Zn)	7440-66-6		0.0451	mg
			Supplier	Iron (Fe)	7439-89-6		0.8838	mg
			Supplier	Copper (Cu)	7440-50-8		36.6698	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0113	mg
Mold Compound-Black	29.02	mg		Epoxy resin	proprietary data		2.1765	mg
			Supplier	Phenolic Resin	Proprietary Data		0.7255	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.1765	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1451	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		23.7964	mg
Plating	0.89	mg	Supplier	Palladium (Pd)	7440-05-3		0.0214	mg
			В	Nickel (Ni)	7440-02-0		0.7832	mg
			Supplier	Gold (Au)	7440-57-5		0.0854	mg
Wire Bond - Au	0.32	mg	Supplier	Gold (Au)	7440-57-5		0.32	mg